

**ST Shenzhen (China)
additional source of Carrier Tape and Cover Tape
for TSSOP 20 package products**

MDG - Microcontrollers Division (MCD)

What are the changes?

Changes described in the below table:

	Current source	Added source
CARRIER TAPE	3M	CPAK
COVER TAPE	3M	CPAK

No FIT change, no need to change manufacturing set-up at customer premises.
Dimension remains within spec and follows international standards EIA 481 (US) / IEC 60286-3 (EU).

No functional change, No quality difference

How can the change be seen?

Carrier Tape and cover Tape may have different visual aspect. See table below.

	Current source 3M Has a glossy finishing	Added source CPAK Has a dull, matt finishing
TAPE		
COVER TAPE		